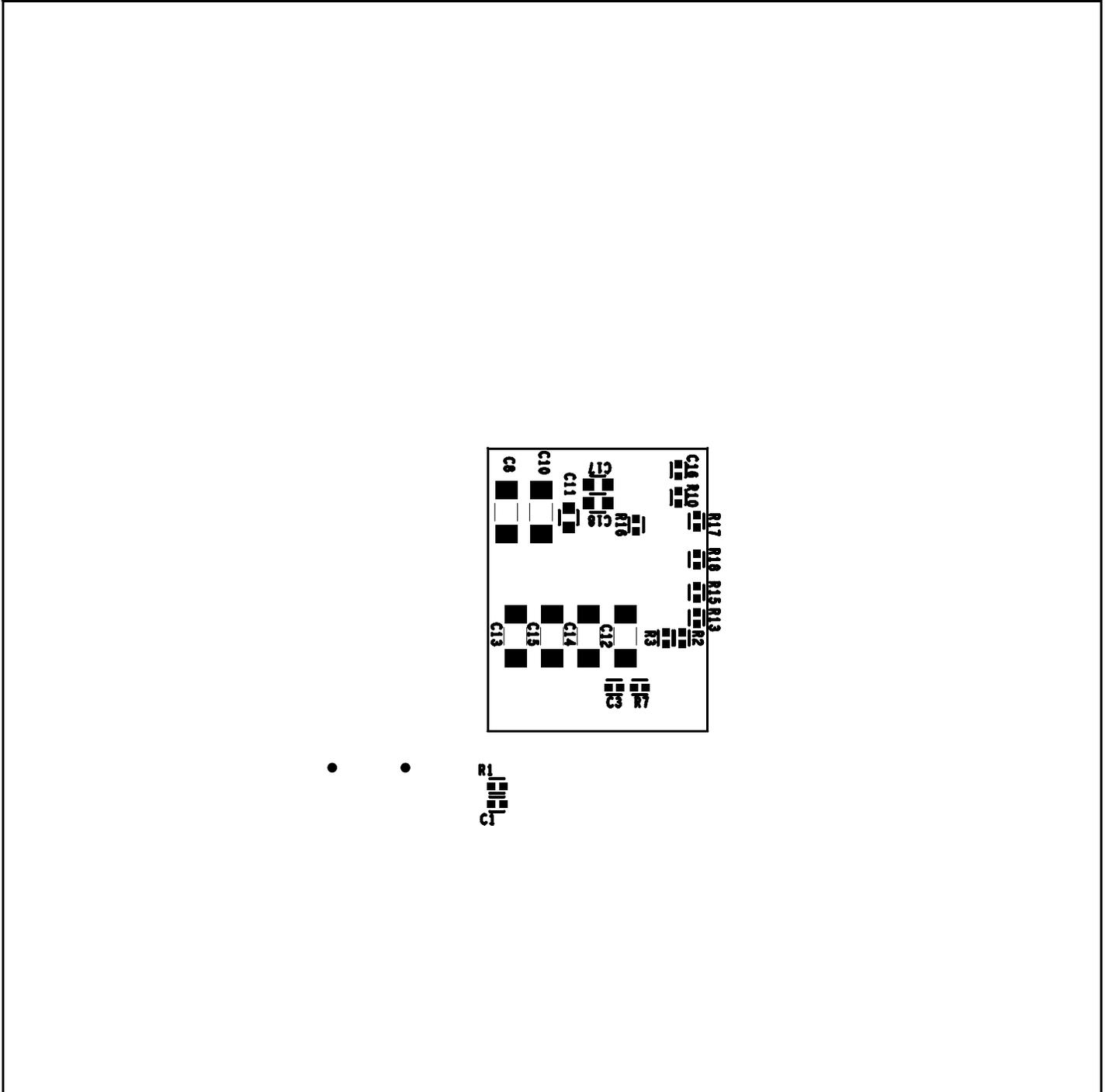
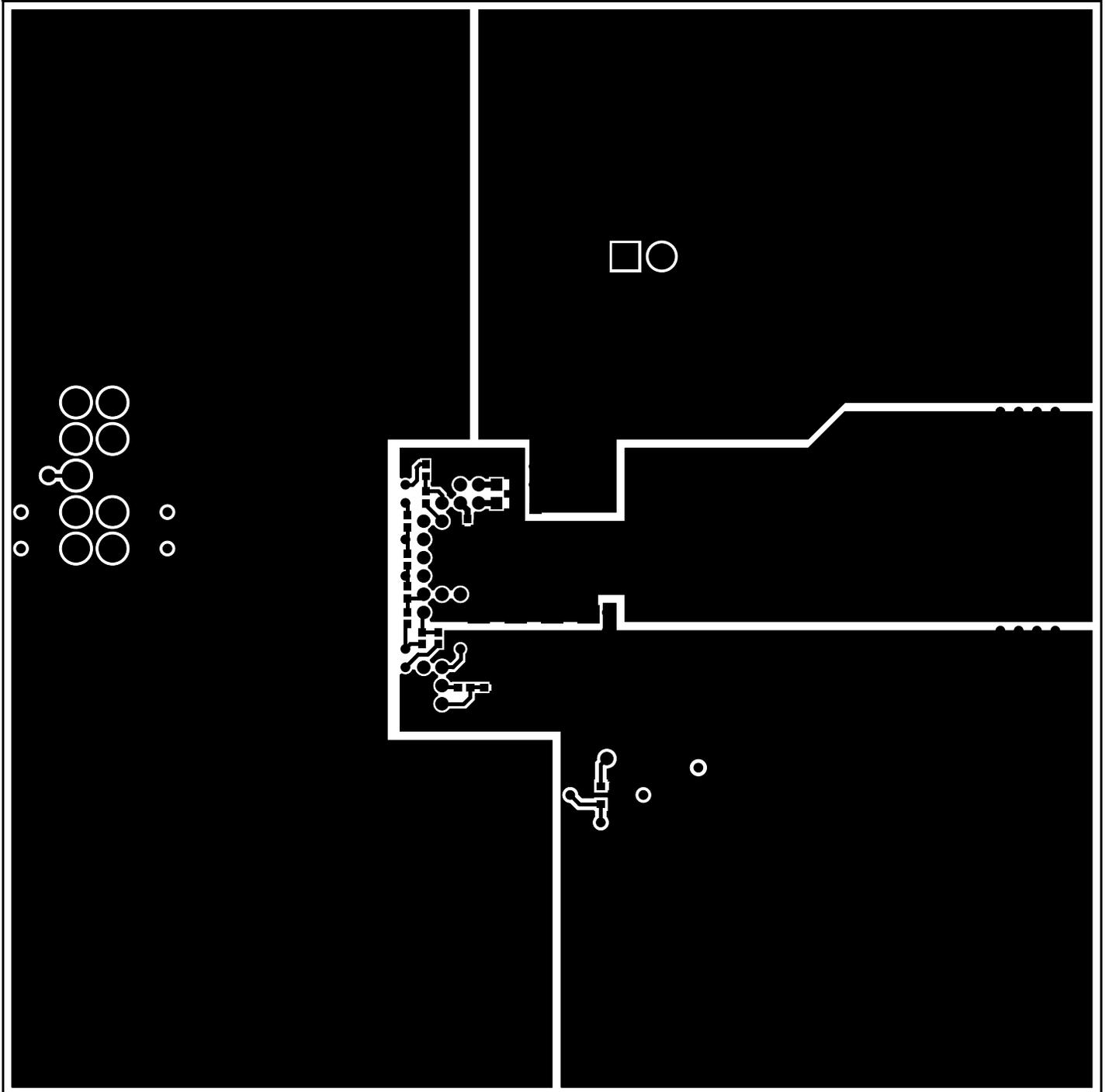
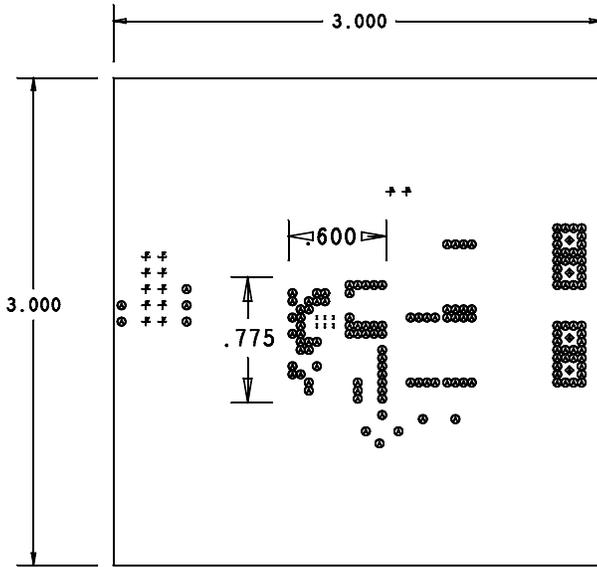


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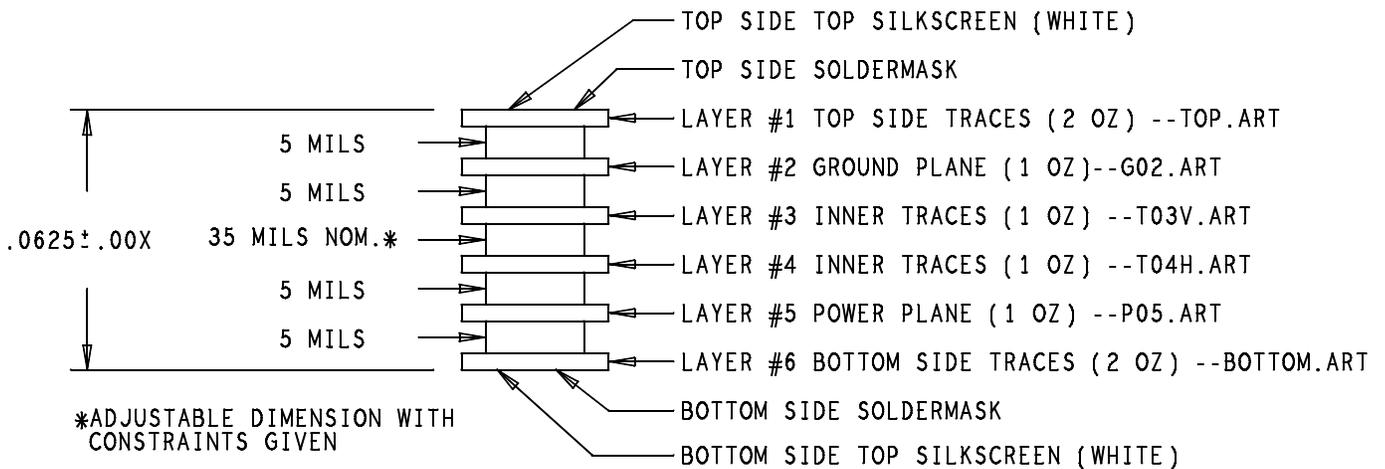
**FABRICATION PARAMETERS:**

THICKNESS: 0.002  
 SILKSCREEN: BOTH  
 SOLDERMASK: BOTH  
 COPPER WEIGHT: 2 OZ (EXT) / 1 OZ (INT)  
 RESIN TYPE: 433  
 MIN TRACE/WP: 0.005/0.005  
 LAYER COUNT: 6 LAYERS

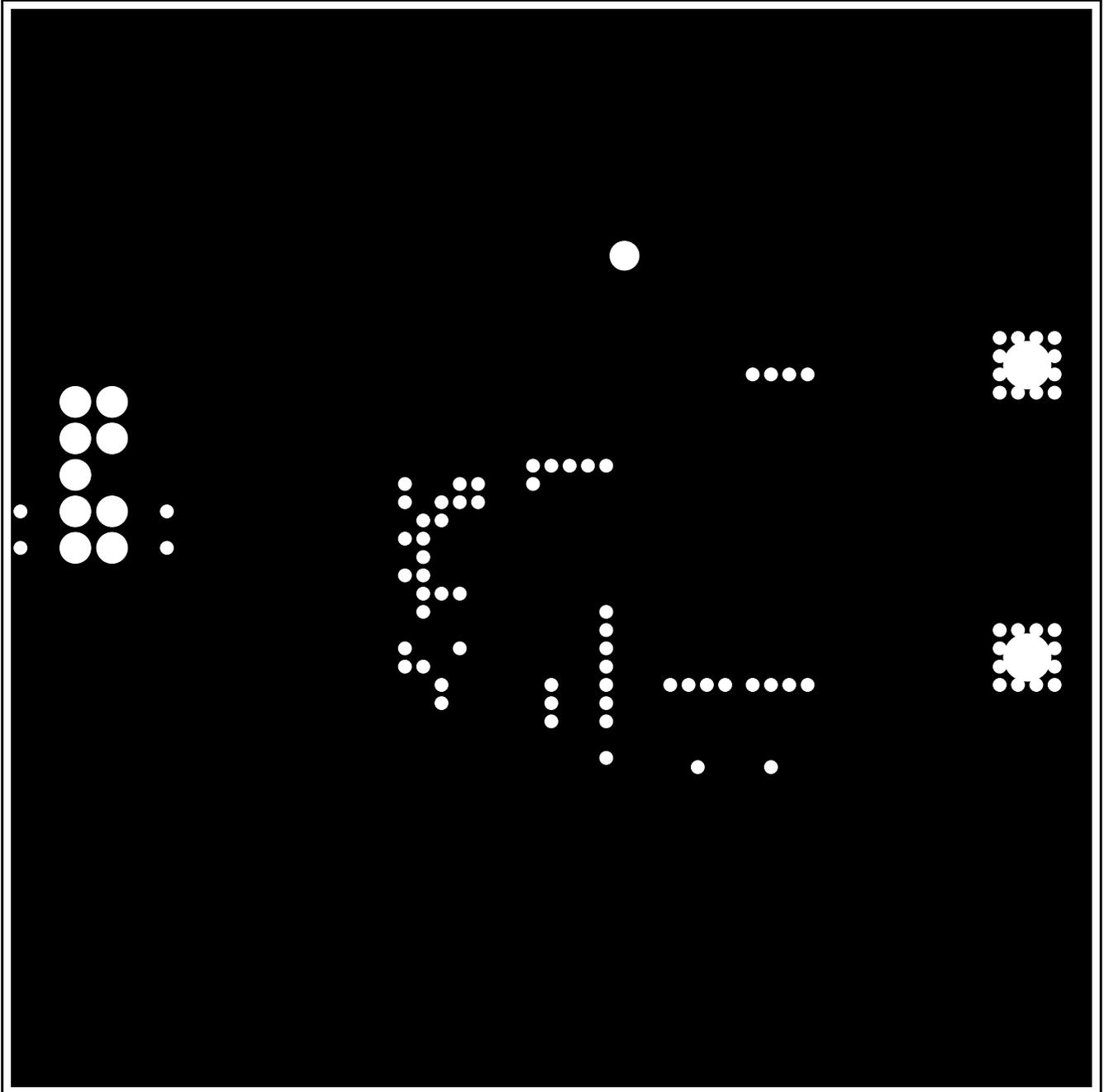
**NOTES: UNLESS OTHERWISE SPECIFIED**

1. MATERIAL: ALL MATERIALS, INCLUDING BUT NOT LIMITED TO BASE LAMINATE, BONDING MATERIALS AND SOLDERMASK COATINGS FORMING THE FINISHED PRINTED CIRCUIT BOARD SHALL MEET UL-796 REQUIREMENTS AND BE ROHS COMPLIANT AND HAVE A FLAMMABILITY OF 94V-0. PLASTIC SHEET, LAMINATED METAL CLAD, TPO BOND, BASE MATERIAL NON-TYPE FR-4 GLASS EPOXY RESIN, COPPER-CLAD IN ACCORDANCE WITH 6 LAYER STACK-UP, COMPLIANT WITH LEAD FREE PROCESS.
2. BASE LAMINATE: SOLDERMASK OVER BASE COPPER (SMDCC) USING 130WID PHOTO-IMAGEABLE SOLDERMASK IN ACCORDANCE WITH IPC-6014.
3. SOLDERMASK: HOLES REQUIRING PLATING, SEE HOLE CHART, TO HAVE 1 OZ. (0.0014) MIN. THK MIN. THICK COPPER.
4. PLATING: PLATE WITH ROHS COMPLIANT, DIMENSION SILVER PREFERRED, DIMENSION TIN OR Sn/Ag/Cu, WITH MIN FILM, 0.0005" +/- 0.0005" THICK MIN ALL EXPOSED AREAS AS COATED, NO ACTIVE FLUXES ARE ACCEPTABLE.
5. FINISH: IF REQUIRED, SILKSCREEN LEGEND(S) WITH WHITE NON-CONDUCTIVE EPOXY INK. BOARD MUST BEAR VENDOR'S IDENTIFICATION CODE (ETCH OR WHITE NON-CONDUCTIVE INK). LOCATION OPTIONAL.
6. LEGEND: PCB BOARD SHALL BE MANUFACTURED PER IPC-A-600 CLASS 2 REQUIREMENTS OR BETTER.
7. MARKING: PCB VENDOR IS REQUIRED TO RETURN ANY AND ALL DOCUMENTS SUPPLIED OR ULTIMATELY PURCHASED BY TEXAS INSTRUMENTS UPON COMPLETION OF PURCHASE ORDER.
8. WORKMANSHIP: HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFTER PLATING UNLESS OTHERWISE NOTED.
9. DOCUMENTATION: ANY METAL TR BORDER AREA INCLUDING PART NUMBER, DATE/CODE AND/OR REVISION LETTERS MUST BE COVERED WITH SOLDERMASK.
10. DRILL SIZES: HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFTER PLATING UNLESS OTHERWISE NOTED.
11. PANEL BORDER: ANY METAL TR BORDER AREA INCLUDING PART NUMBER, DATE/CODE AND/OR REVISION LETTERS MUST BE COVERED WITH SOLDERMASK.
12. PROCESS CHANGES: NO DIMENSIONAL, MATERIAL, OR PROCESS CHANGES ARE ALLOWED WITHOUT PRIOR EXPLICIT WRITTEN PERMISSION FROM TEXAS INSTRUMENTS.

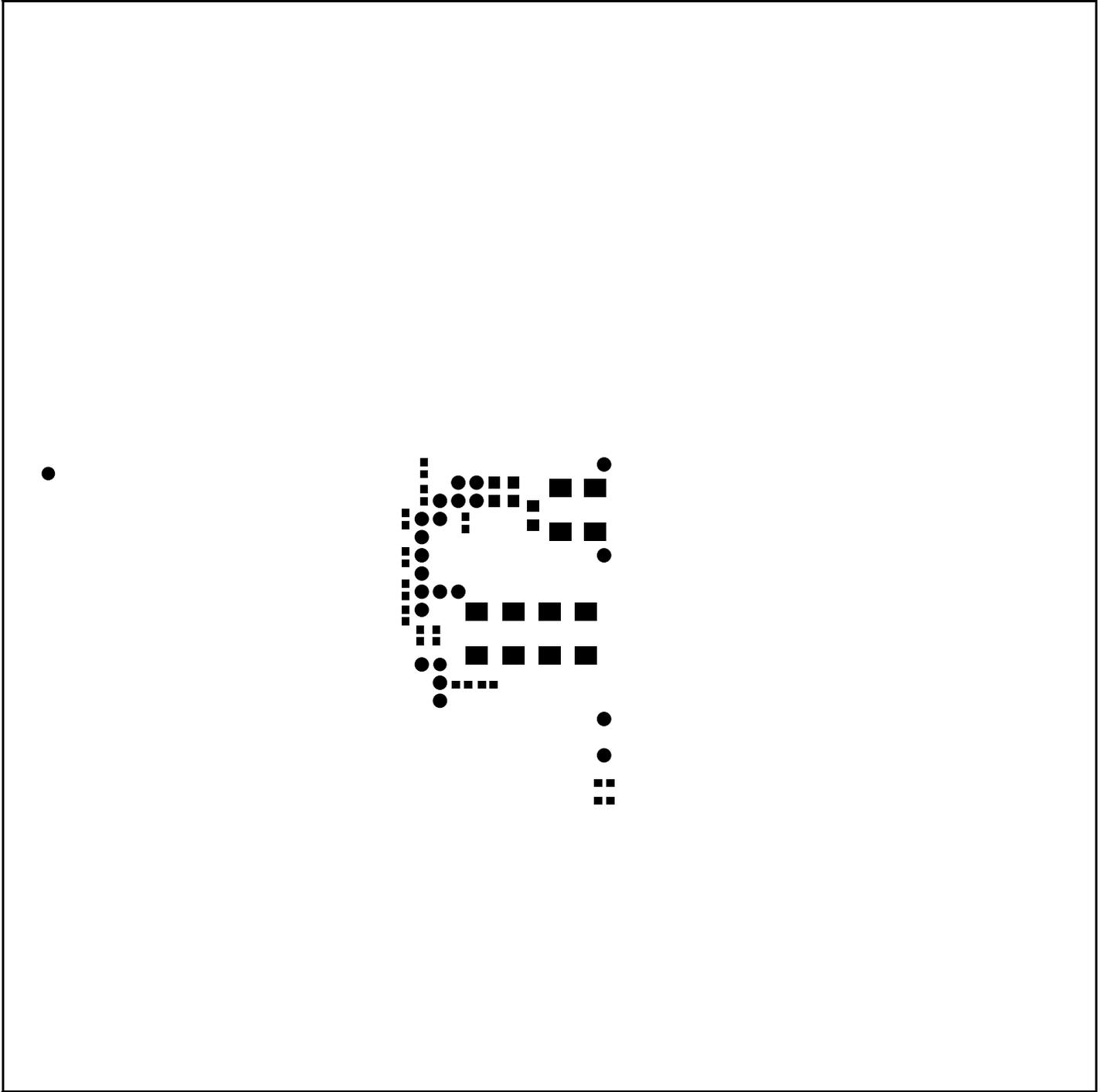
DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
.	8.0	+2.0/-5.0	PLATED	6
o	10.0	+3.0/-3.0	PLATED	135
+	50.0	+3.0/-3.0	PLATED	2
+	55.0	+3.0/-3.0	PLATED	10
◆	60.0	+3.0/-3.0	PLATED	4

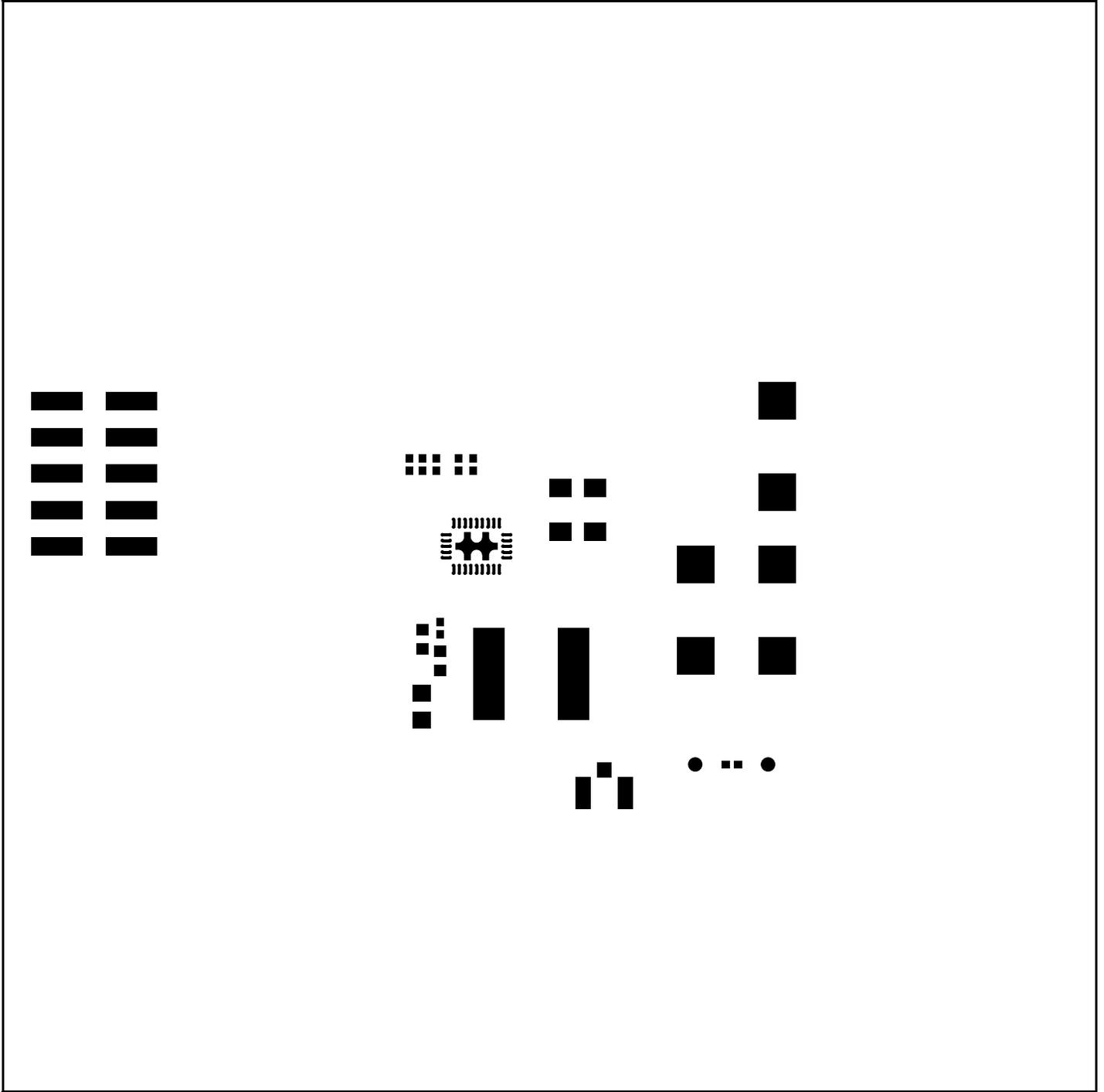


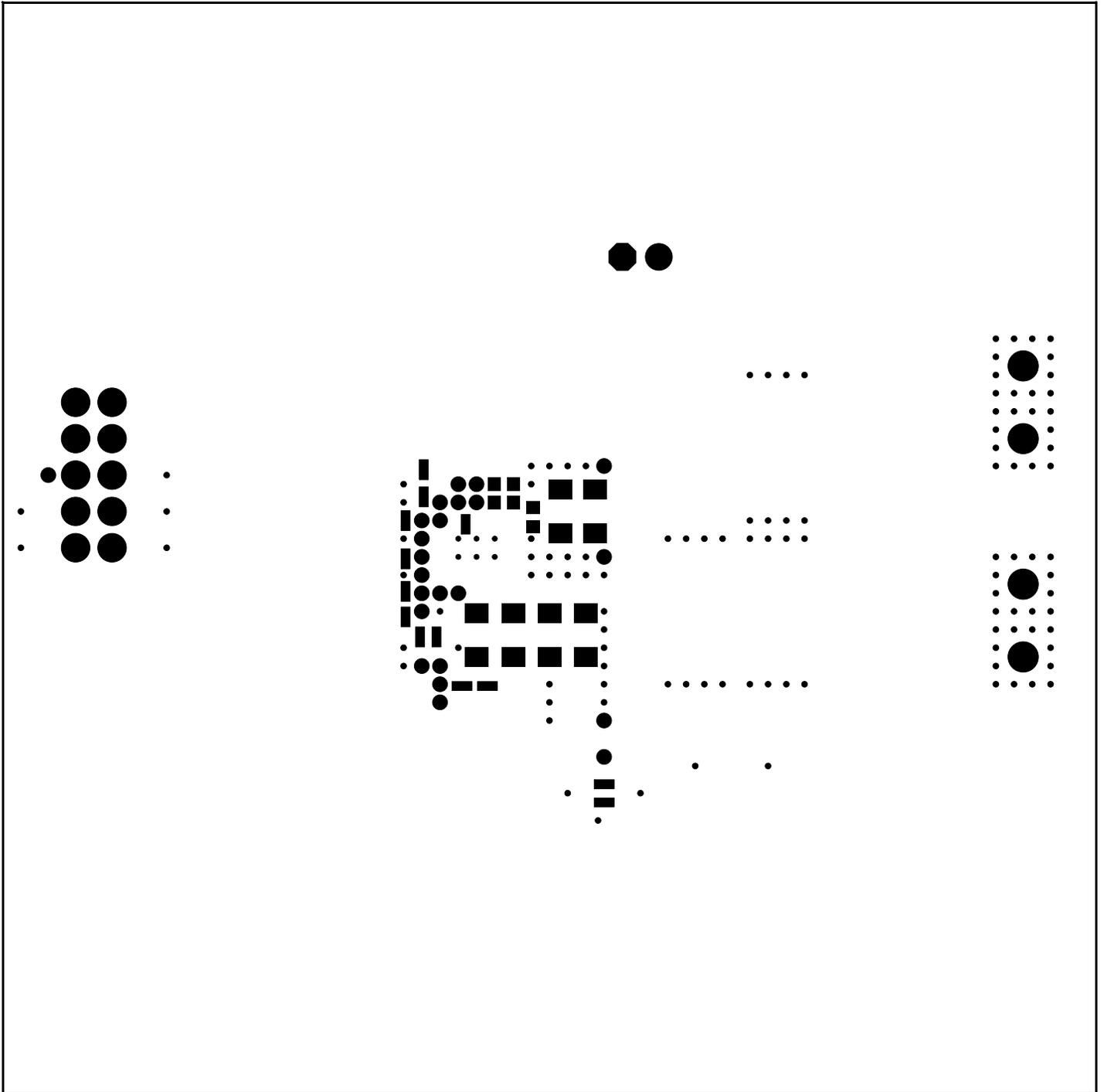
VIEW X-X XX  
 SCALE = NONE

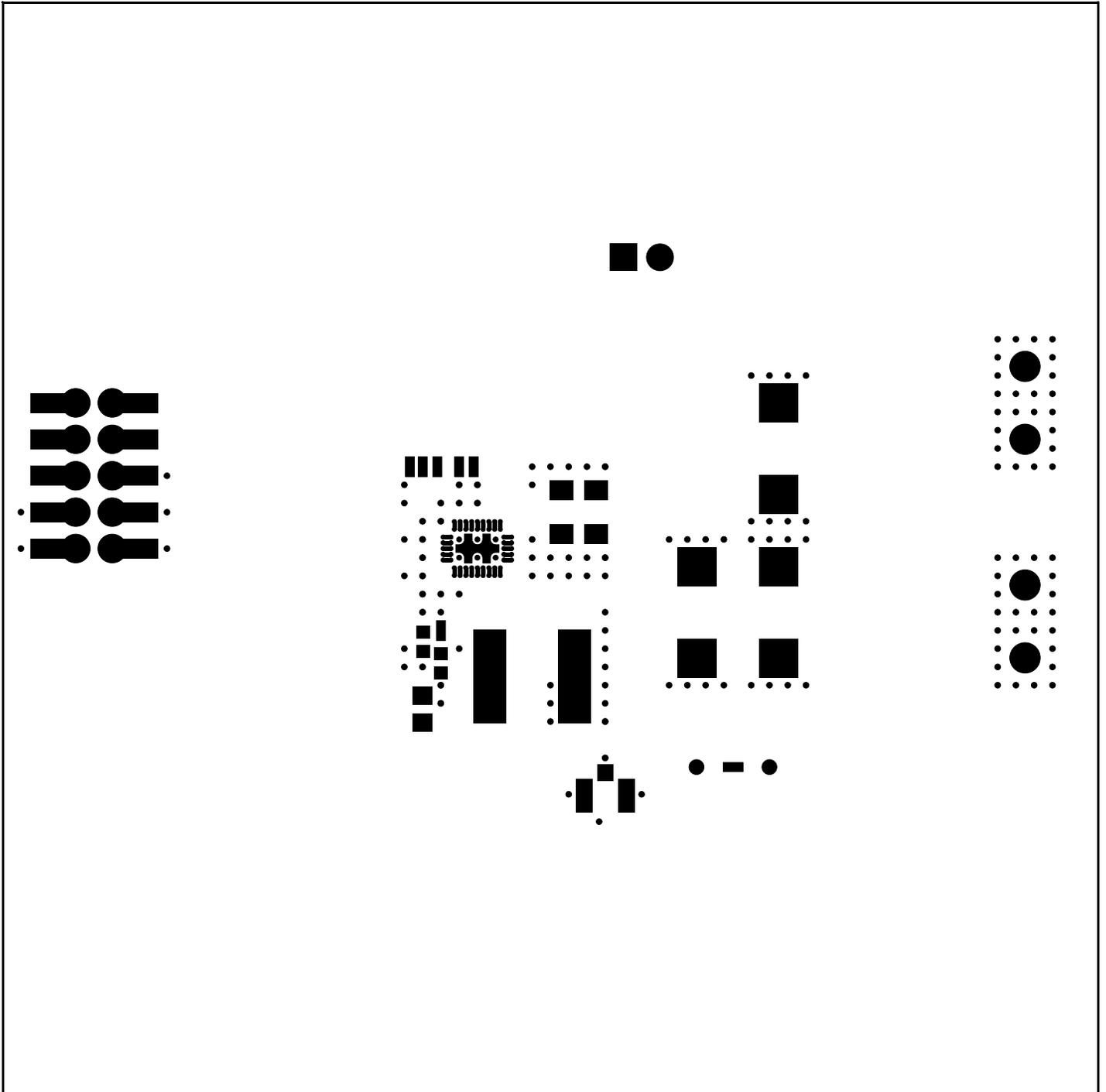


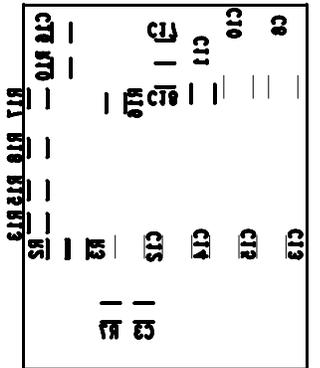
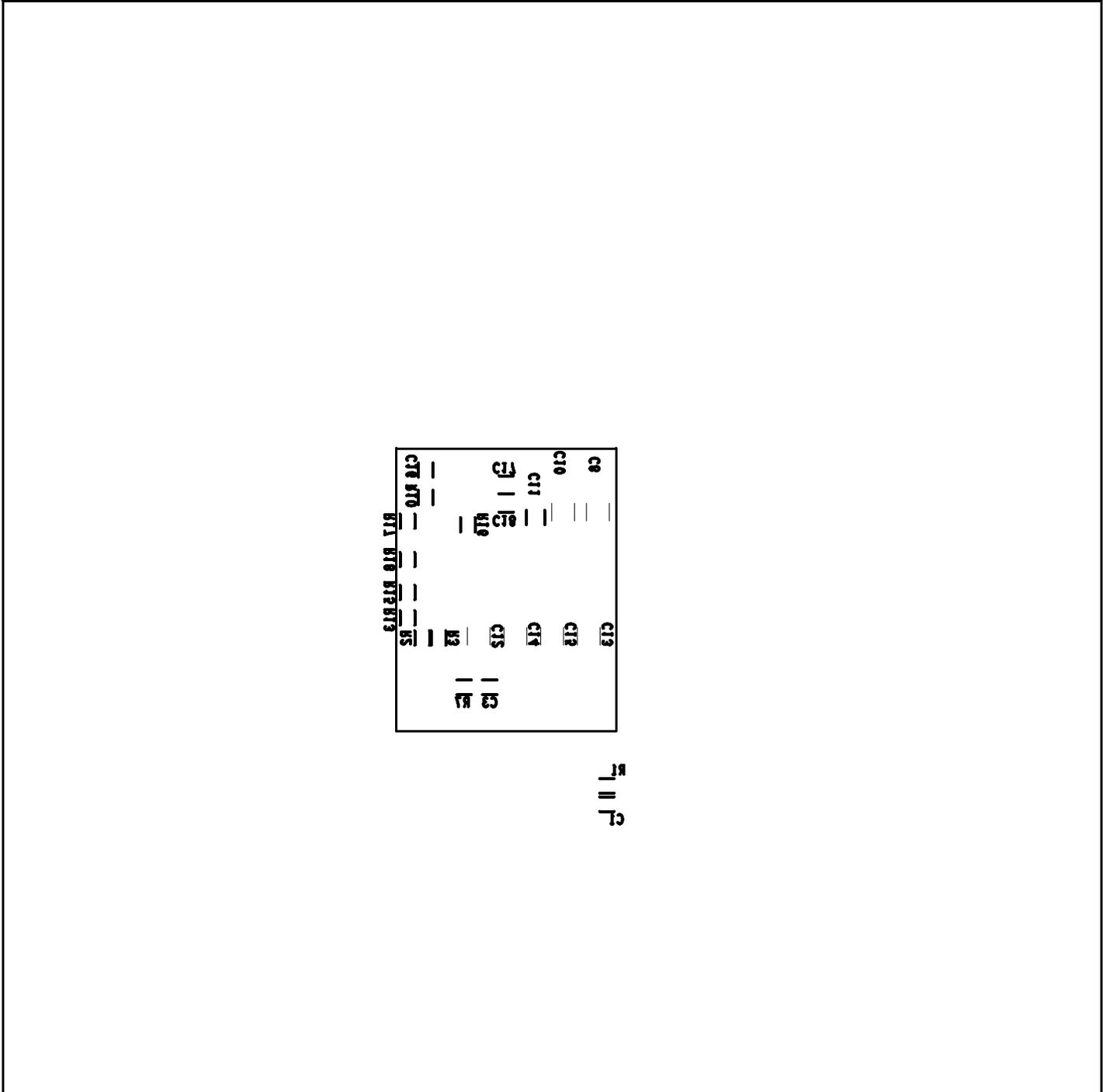




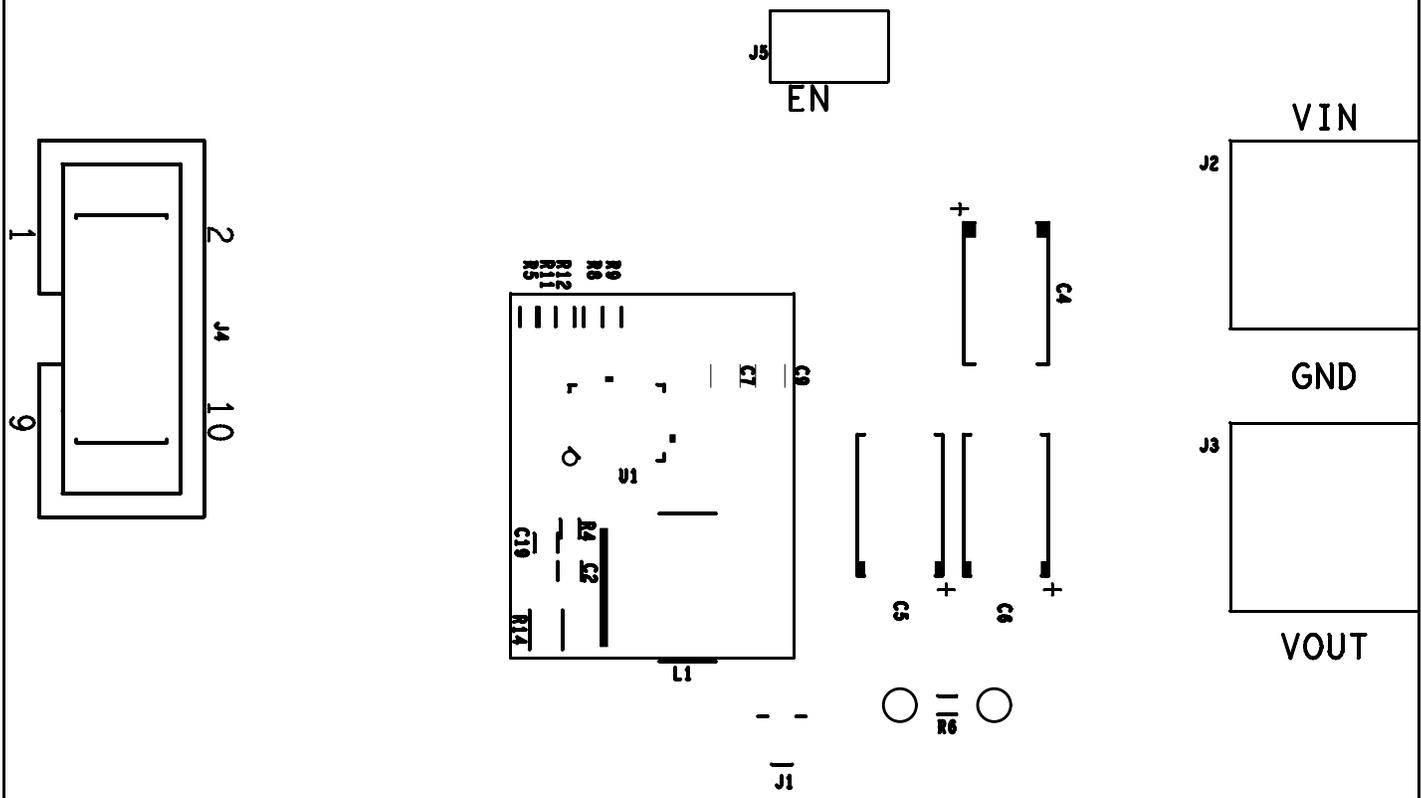




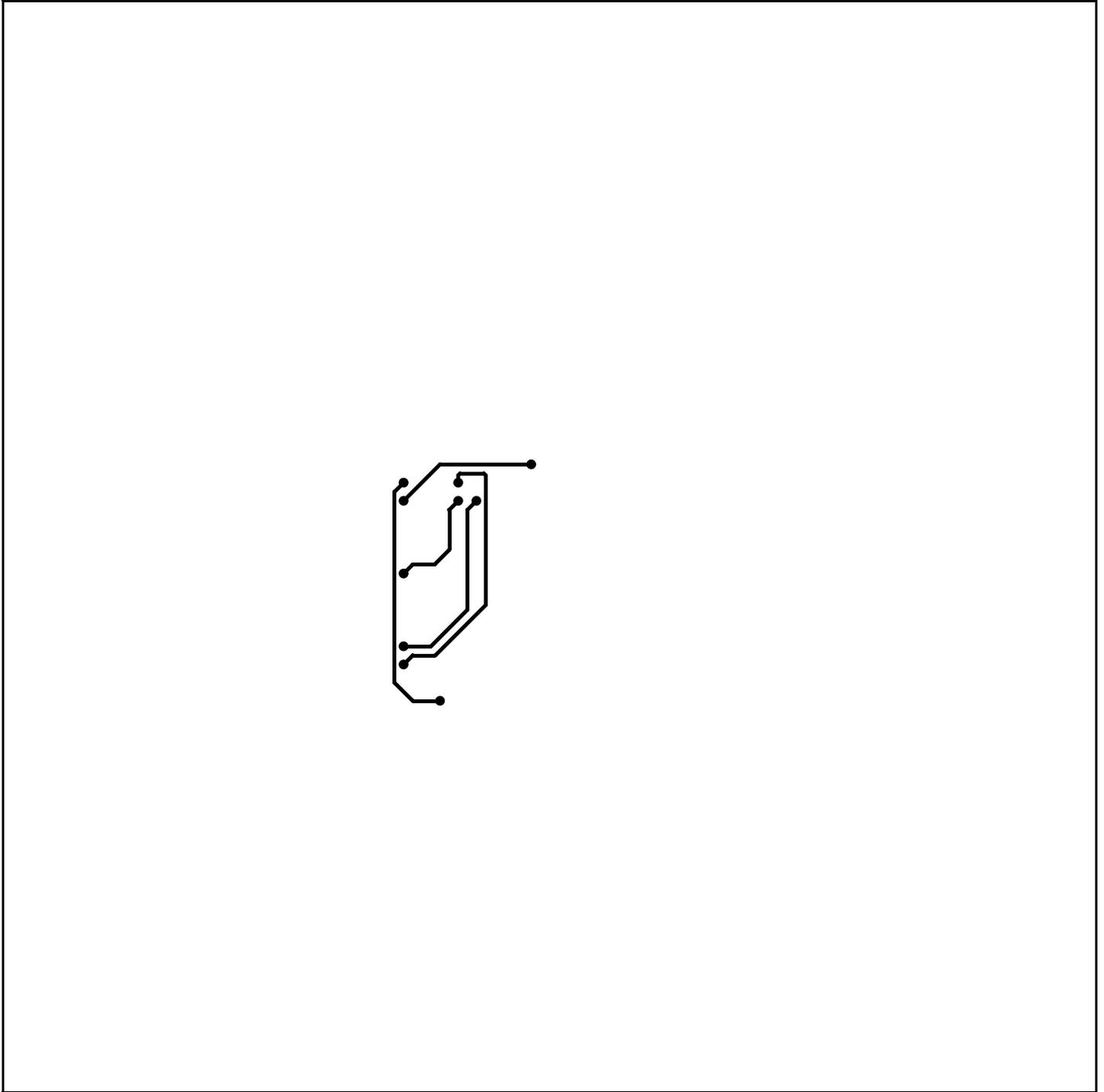


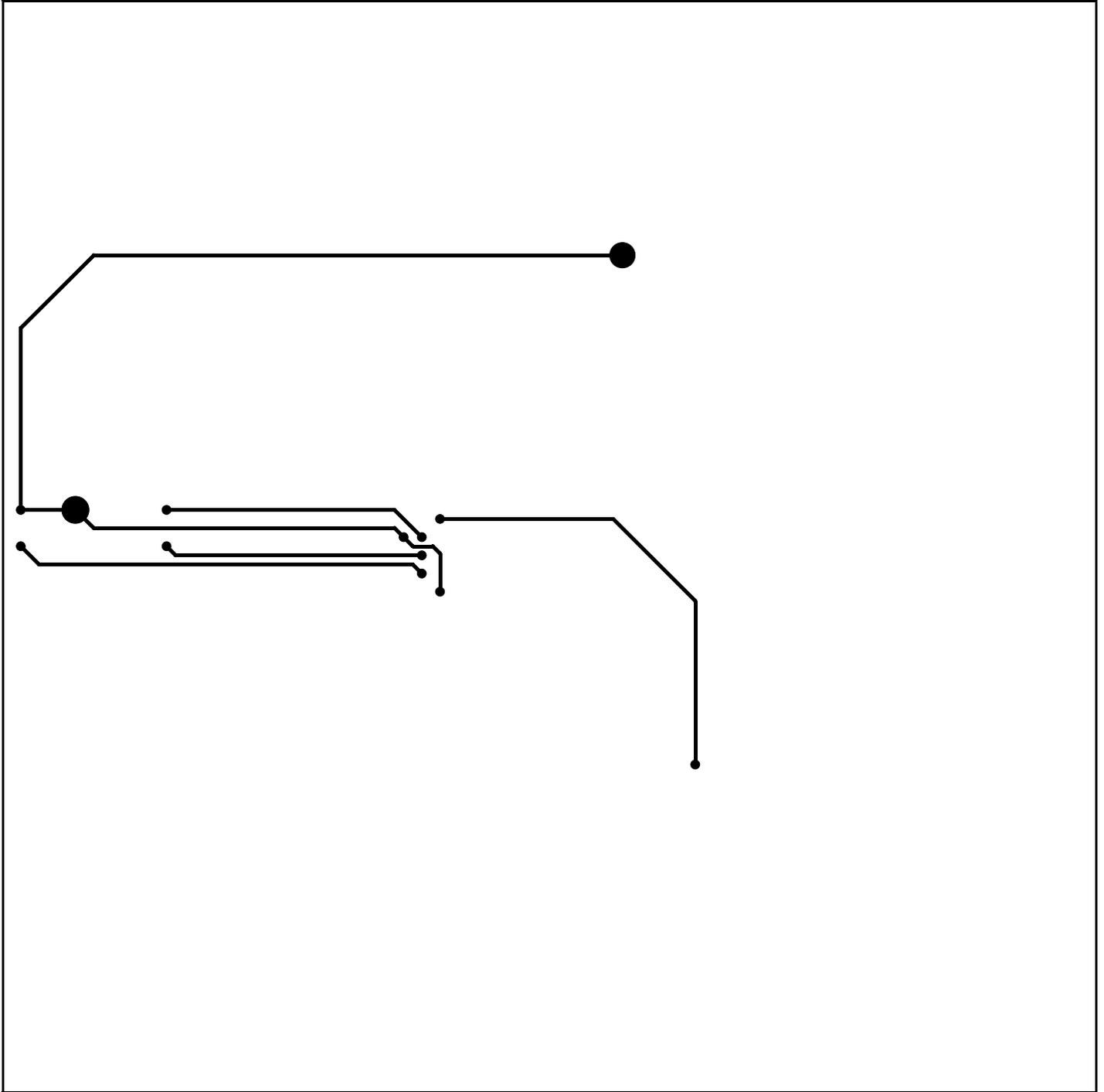


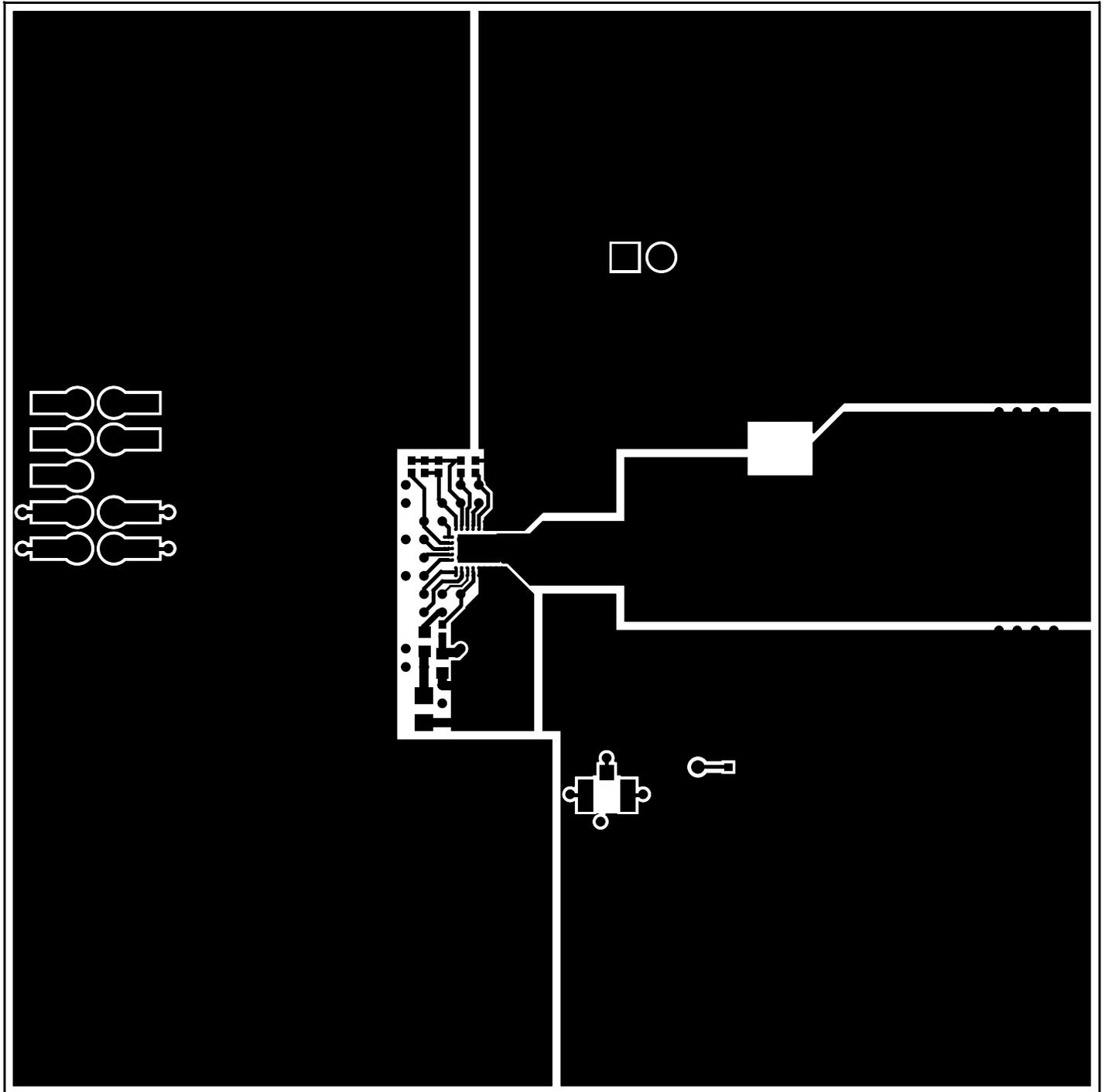
R1 R2

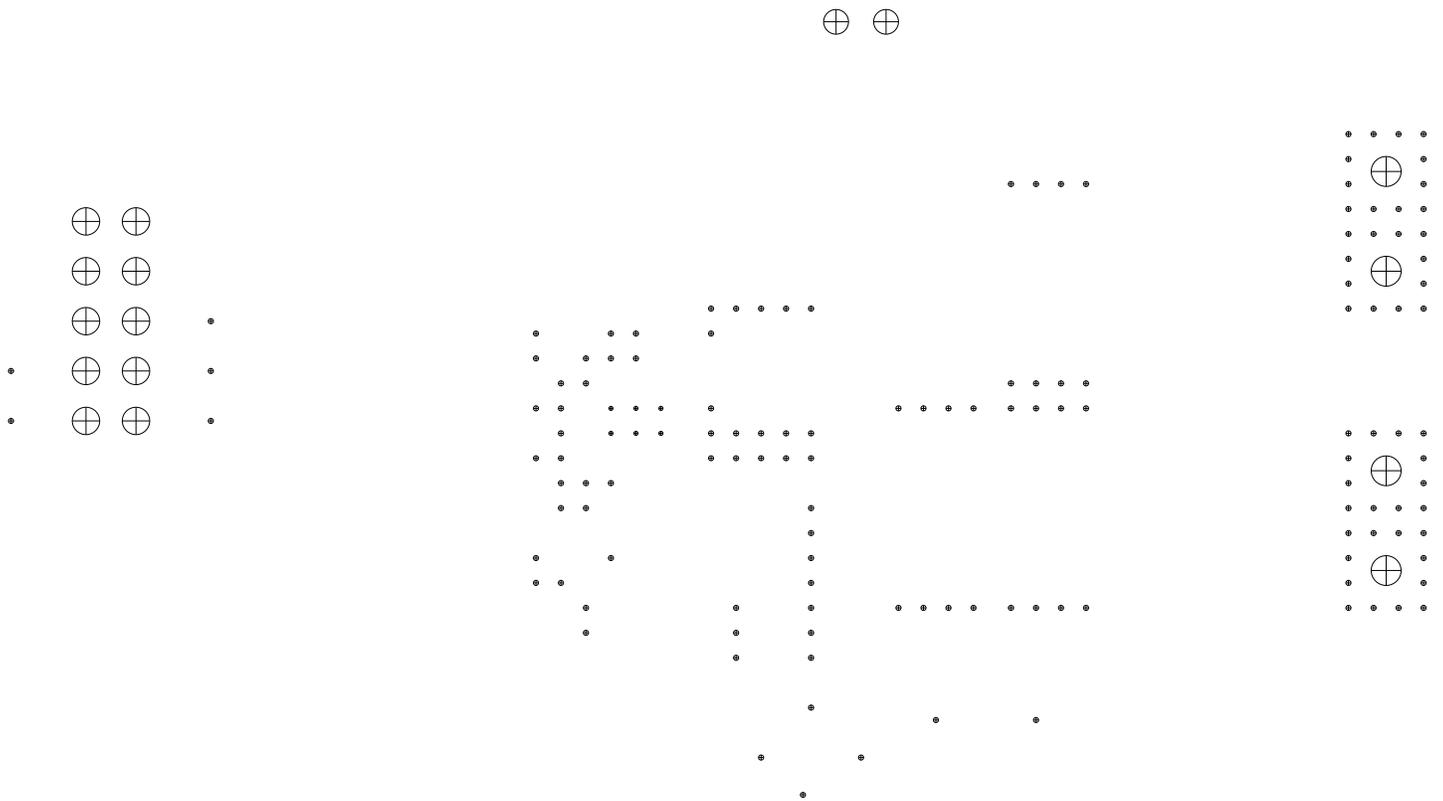


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